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ISO  
**14165-147**

First edition

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## Information technology — Fibre channel —

Part 147:  
**Physical interfaces - 7 (FC-PI-7)**

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## Contents

<b>1 Scope .....</b>	<b>1</b>
<b>2 Normative references .....</b>	<b>1</b>
2.1 General .....	1
2.2 Normative references .....	1
2.2.1 Approved references.....	1
2.2.2 References under development .....	2
<b>3 Definitions and conventions.....</b>	<b>3</b>
3.1 Definitions .....	3
3.2 Editorial conventions .....	7
3.2.1 Conventions .....	7
3.2.2 Keywords .....	8
3.2.3 Abbreviations, acronyms, and symbols.....	8
3.2.3.1 Acronyms and other abbreviations.....	9
3.2.3.2 Signaling rate abbreviations .....	10
<b>4 FC-PI-7 functional characteristics .....</b>	<b>11</b>
4.1 General characteristics .....	11
4.2 Compliance test points .....	11
4.3 FC-0 functions .....	13
4.3.1 Transmitter functions.....	13
4.3.2 Receiver functions .....	13
4.4 Limitations on invalid code .....	14
4.5 Receiver stabilization time.....	14
4.6 Loss of signal (Rx _LOS) function .....	14
4.7 Speed agile ports that support speed negotiation and training .....	14
4.8 Transmission codes.....	14
4.9 Frame scrambling and emission lowering protocol .....	14
4.10 Forward error correction (FEC) .....	15
4.11 Bit error ratio per link locations and segments.....	15
4.12 FC-PI-7 variants .....	16
<b>5 Optical interface specification .....</b>	<b>17</b>
5.1 TxRx connections .....	17
5.2 Laser safety issues .....	17
5.3 Optical signal modulation format .....	17
5.4 SM data links .....	18
5.4.1 SM general information.....	18
5.4.2 SM optical output interface .....	18
5.4.3 SM optical input interface .....	18
5.4.4 Transmitter transition time.....	18
5.4.5 TDECQ Test .....	18
5.4.6 SECQ Measurement.....	18
5.4.7 SRS Test .....	18
5.5 MM data links .....	20
5.5.1 MM general information .....	20
5.5.2 MM optical output interface .....	20
5.5.3 MM optical input interface .....	20
5.5.4 Transmitter transition time.....	20
5.5.5 TDECQ Test .....	21

5.5.6 SECQ Measurement .....	21
5.5.7 SRS Test .....	21
5.6 SM Cable Plant .....	23
5.6.1 Cable plant overview .....	23
5.6.2 Optical Return Loss .....	23
5.6.3 Connector and Splices .....	24
5.7 MM Cable Plant .....	24
5.7.1 Cable plant overview .....	24
5.7.2 Optical Return Loss .....	24
5.7.3 Connector and Splices .....	24
<b>6 Electrical interface specification - single lane segments.....</b>	<b>25</b>
6.1 General electrical characteristics .....	25
6.2 Compliance test point definitions .....	25
6.2.1 Test method .....	25
6.2.2 Host test points .....	26
6.2.3 Module test points .....	26
6.2.4 Host input calibration point .....	27
6.2.5 Module input calibration point .....	28
6.3 Transmitted signal characteristics .....	29
6.4 Receive signal characteristics .....	30
6.5 Differential return loss and mode conversion requirements .....	31
6.5.1 Differential return loss .....	31
6.5.2 Common to differential-mode and differential to common-mode conversion .....	31
<b>7 Backplane variant, 64GFC-EA.....</b>	<b>33</b>
7.1 TxRx Connections .....	33
7.2 Test Fixtures .....	33
7.3 Transmitter specification .....	35
7.4 Receiver specification .....	37
7.4.1 Receiver input return loss .....	37
7.4.2 Receiver interference tolerance .....	38
7.4.3 Receiver jitter tolerance .....	39
7.5 Channel Specification .....	39
7.5.1 Channel Operating Margin .....	39
7.5.2 Channel Return Loss .....	41
7.5.3 Channel AC coupling .....	41
<b>Annex A (informative) Optical cable plant usage.....</b>	<b>42</b>
<b>Annex B (informative) Structured cabling environment .....</b>	<b>44</b>
B.1 Specification of operating distances .....	44
B.2 Alternate connection loss operating distances .....	44
<b>Annex C (informative) Electrical channel .....</b>	<b>45</b>

## List of Tables

Table 1 - ISO convention .....	7
Table 2 - Acronyms and other abbreviations.....	9
Table 3 - Signaling rate abbreviations.....	10
Table 4 - BER per link Location / Segment.....	15
Table 5 - Fibre Channel Variants in FC-PI-7.....	16
Table 6 - Single-mode link parameters (OS2).....	19
Table 7 - Multimode link parameters.....	22
Table 8 - Maximum value of each discrete reflectance.....	23
Table 9 - General electrical characteristics.....	25
Table 10 - Transmitter compliance requirements at nominal signal rate of 28 900 MBd .....	29
Table 11 - Receiver compliance requirements .....	30
Table 12 - Transmitter electrical specifications at A .....	35
Table 13 - Summary of receiver characteristics at test point D.....	37
Table 14 - Receiver interference tolerance parameters .....	39
Table 15 - Receiver jitter tolerance parameters .....	39
Table 16 - Channel Operating Margin (COM) parameters .....	40
Table A.1 - Worst case (nominal bandwidth) multimode cable link power budget .....	42
Table A.2 - Worst-case single mode cable link power budget .....	43
Table B.1 - 64GFC-SW (MM) and 64GFC-LW (SM) max operating distance & loss budget for different connection losses .....	44
Table C.1 - Informative host to module channel characteristics, high loss channel .....	45

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## List of Figures

Figure 1 - Fibre Channel hierarchy .....	12
Figure 2 - Compliance points for 64GFC PMDs .....	13
Figure 3 - BER per Section .....	15
Figure 4 - Optical Eye Diagram of a PAM4 Signal .....	17
Figure 5 - Host Compliance Board .....	26
Figure 6 - Module Compliance Board .....	27
Figure 7 - Host input calibration point C" .....	27
Figure 8 - Module input calibration point B" .....	28
Figure 9 - SDD11 and SDD22 for all compliance points .....	31
Figure 10 - SDC22 for transmitter output and SCD11 for receiver input .....	32
Figure 11 - Test fixture and test points .....	33
Figure 12 - Test fixture reference insertion loss .....	34
Figure 13 - Test fixture differential return loss .....	34
Figure 14 - Transmitter and receiver differential return loss limit .....	36
Figure 15 - Transmitter common-mode return loss .....	37
Figure 16 - Receiver differential to common-mode return loss limit .....	38
Figure 17 - Channel return loss limit .....	41
Figure C.1 - Typical FC-PI-7 electrical channel construction .....	45
Figure C.2 - FC-PI-7 full channel electrical reference model, high loss channel .....	45

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This standard was developed by Task Group T11.2 of Accredited Standards Committee INCITS during 2016, 2017, and 2018. The standards approval process will be started in 2018. This document includes annexes that are informative and are not considered part of the standard.

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